

Features

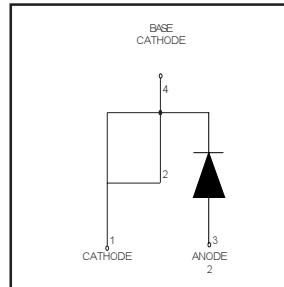
- Ultrafast Recovery
- Ultrasoft Recovery
- Very Low I_{RRM}
- Very Low Q_{rr}
- Specified at Operating Conditions
- Lead-Free

Benefits

- Reduced RFI and EMI
- Reduced Power Loss in Diode and Switching Transistor
- Higher Frequency Operation
- Reduced Snubbing
- Reduced Parts Count

Description

International Rectifier's HFA08PB60 is a state of the art center tap ultra fast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 volts and 8 amps continuous current, the HFA08PB60 is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultra fast recovery time, the HEXFRED product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED HFA08PB60 is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.



$V_R = 600V$
$V_F(\text{typ.})^* = 1.4V$
$I_{F(AV)} = 8.0A$
$Q_{rr}(\text{typ.}) = 65nC$
$I_{RRM} = 3.5A$
$t_{rr}(\text{typ.}) = 18ns$
$di_{(rec)M}/dt(\text{typ.})^* = 210A/\mu s$



TO-247AC (Modified)

Absolute Maximum Ratings

	Parameter	Max	Units
V_R	Cathode-to-Anode Voltage	600	V
$I_F @ T_C = 25^\circ C$	Continuous Forward Current		A
$I_F @ T_C = 100^\circ C$	Continuous Forward Current	8.0	
I_{FSM}	Single Pulse Forward Current	60	
I_{FRM}	Maximum Repetitive Forward Current	24	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	36	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	14	
T_J	Operating Junction and	-55 to +150	C
T_{STG}	Storage Temperature Range		

* 125°C

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min	Typ	Max	Units	Test Conditions
V_{BR}	Cathode Anode Breakdown Voltage	600	—	—	V	$I_R = 100\mu\text{A}$
V_{FM}	Max Forward Voltage	—	1.4	1.7	V	$I_F = 8.0\text{A}$
		—	1.7	2.1		$I_F = 16\text{A}$ See Fig. 1
		—	1.4	1.7		$I_F = 8.0\text{A}$, $T_J = 125^\circ\text{C}$
I_{RM}	Max Reverse Leakage Current	—	0.3	5.0	μA	$V_R = V_R$ Rated See Fig. 2
		—	100	500		$T_J = 125^\circ\text{C}$, $V_R = 0.8 \times V_R$ Rated
C_T	Junction Capacitance	—	10	25	pF	$V_R = 200\text{V}$ See Fig. 3
L_S	Series Inductance	—	8.0	—	nH	Measured lead to lead 5mm from package body

Dynamic Recovery Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min	Typ	Max	Units	Test Conditions
t_{rr}	Reverse Recovery Time		18		ns	$I_F = 1.0\text{A}$, $di_F/dt = 200\text{A}/\mu\text{s}$, $V_R = 30\text{V}$
t_{rr1}	See Fig. 5, 10		37	55		$T_J = 25^\circ\text{C}$
t_{rr2}			55	90		$T_J = 125^\circ\text{C}$
I_{RRM1}	Peak Recovery Current See Fig. 6		3.5	5.0	A	$T_J = 25^\circ\text{C}$
I_{RRM2}			4.5	8.0		$T_J = 125^\circ\text{C}$
Q_{rr1}	Reverse Recovery Charge See Fig. 7		65	138	nC	$T_J = 25^\circ\text{C}$
Q_{rr2}			124	360		$T_J = 125^\circ\text{C}$
$di_{(rec)M}/dt1$	Peak Rate of Fall of Recovery Current During t_b See Fig. 8		240		A/ μs	$T_J = 25^\circ\text{C}$
$di_{(rec)M}/dt2$			210			$T_J = 125^\circ\text{C}$

Thermal - Mechanical Characteristics

	Parameter	Min	Typ	Max	Units
$T_{lead}^{①}$	Lead Temperature	—	—	300	$^\circ\text{C}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	—	—	3.5	K/W
$R_{\theta JA}^{②}$	Thermal Resistance, Junction to Ambient	—	—	40	
$R_{\theta CS}^{③}$	Thermal Resistance, Case to Heat Sink	—	0.25	—	
Wt	Weight	—	6.0	—	g
		—	0.21	—	(oz)
	Mounting Torque	6.0	—	12	Kg-cm
		5.0	—	10	lbf·in

① 0.063 in. from Case (1.6mm) for 10 sec

② Typical Socket Mount

③ Mounting Surface, Flat, Smooth and Greased

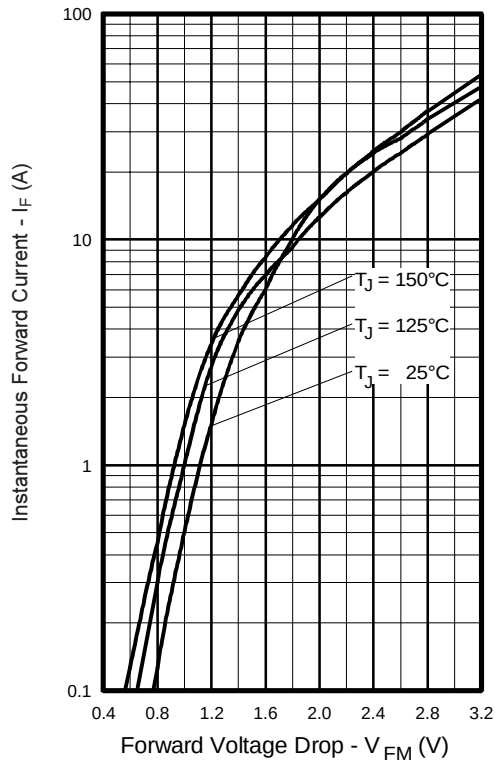


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

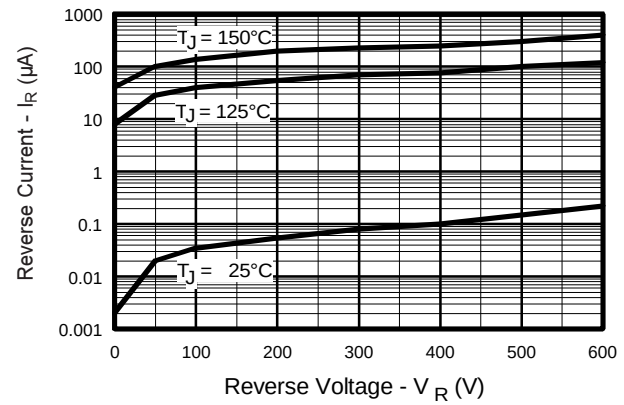


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

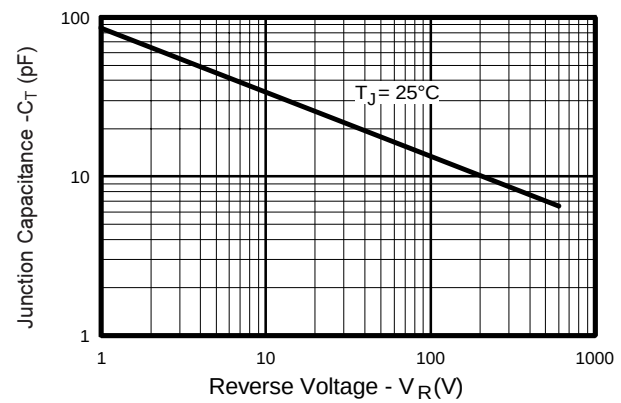


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

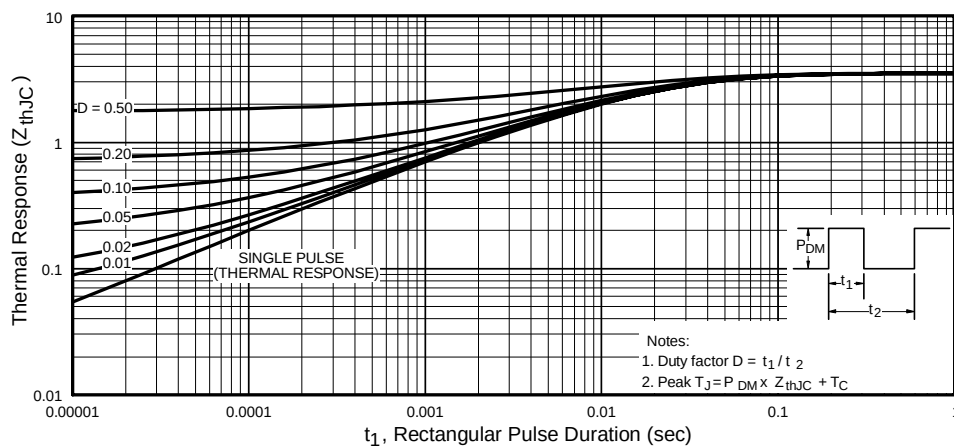


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

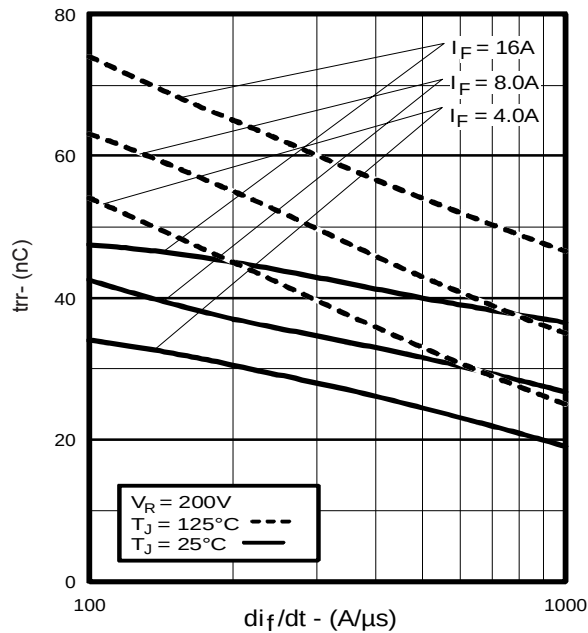


Fig. 5 - Typical Reverse Recovery vs. di_f/dt ,
(per Leg)

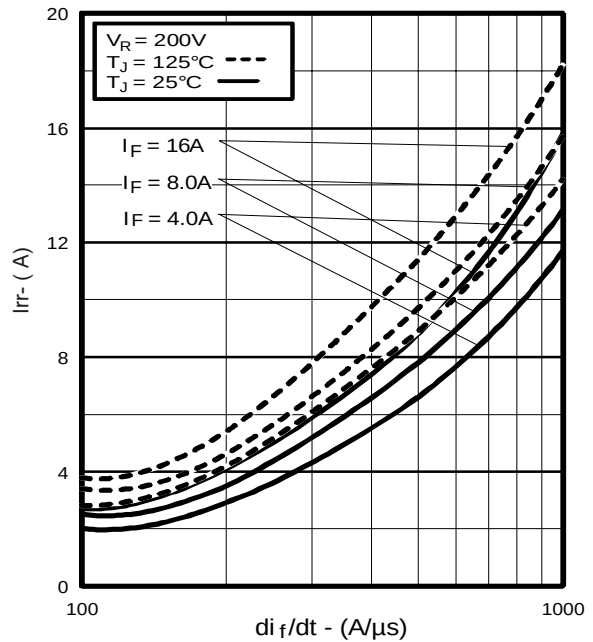


Fig. 6 - Typical Recovery Current vs. di_f/dt ,
(per Leg)

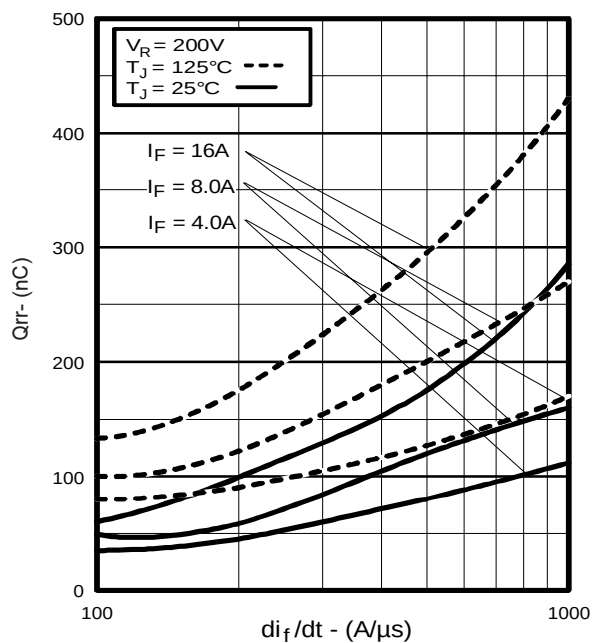


Fig. 7 - Typical Stored Charge vs. di_f/dt ,
(per Leg)

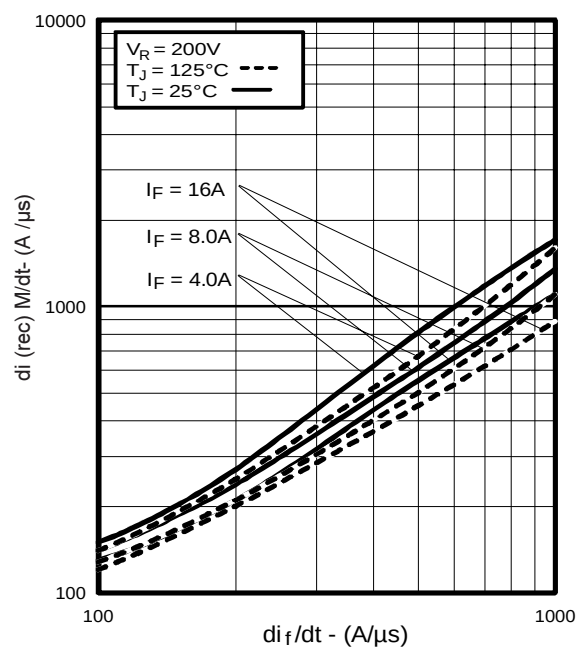


Fig. 8 - Typical $di_{(rec)}M/dt$ vs. di_f/dt ,
(per Leg)

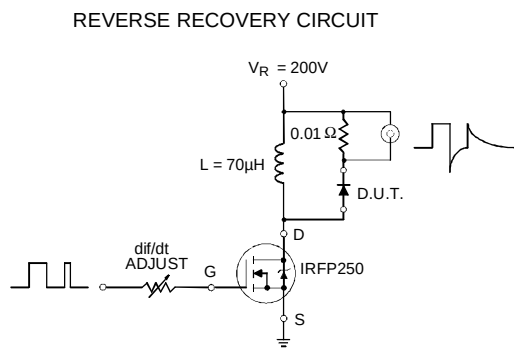


Fig. 9 - Reverse Recovery Parameter Test Circuit

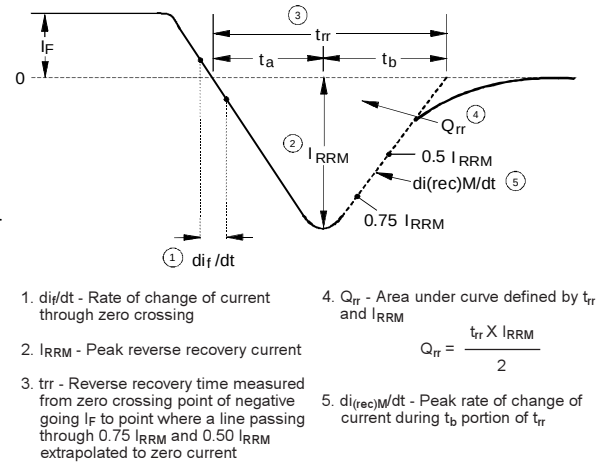
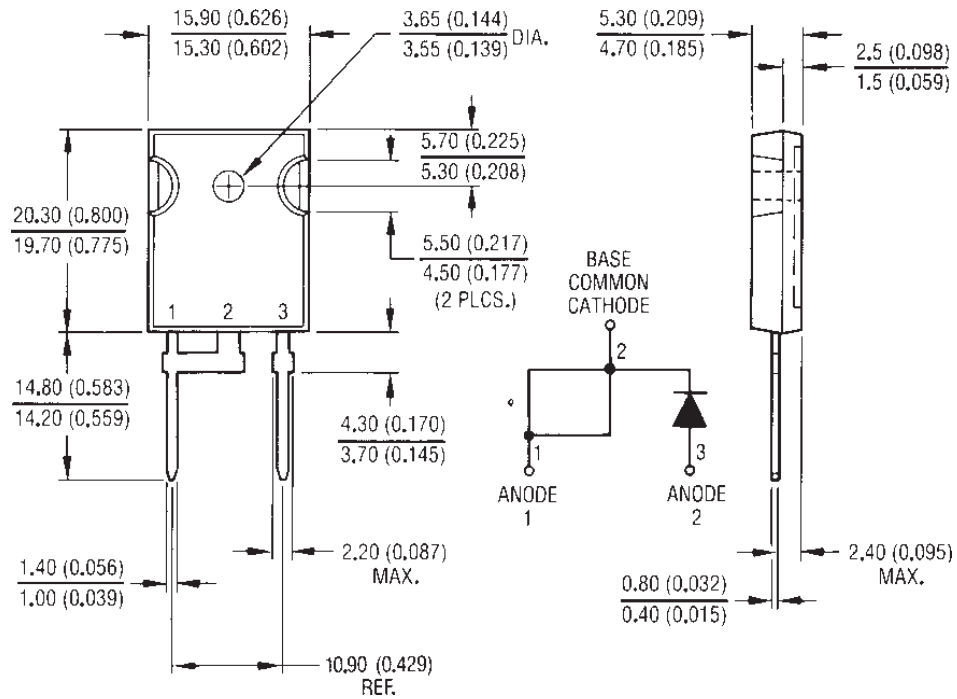


Fig. 10 - Reverse Recovery Waveform and Definitions

HFA08PB60PbF

International
IR Rectifier

Outline Table



Conforms to JEDEC Outline TO-247AC MODIFIED
Dimensions in millimeters and inches

*Note: Marking "P" indicates Lead-Free

International
IR Rectifier

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